



# Advanced CMOS TTL Input – 54ACT04

Hex Inverter Gate with LSTTL compatible inputs in bare die form

Rev 1.1  
08/03/21

## Description

The 54ACT04 hex inverter gate is fabricated on a 1.5 $\mu$ m advanced 5V CMOS process combining high speed LSTTL performance with CMOS low power. The device contains six independent inverters which perform the Boolean function Y =  $\bar{A}$ . Internal circuitry comprises of three stages and includes buffered output for high noise immunity and stability. Inputs are directly compatible with both standard TTL and CMOS outputs. All inputs are protected against ESD and excess voltage transients

## Features:

- Inputs directly accept TTL
- Outputs directly interface CMOS, NMOS and TTL
- Outputs Source/Sink 24 mA
- Low Input Current: 1 $\mu$ A
- Functionally compatible with bipolar 54LS04
- Lower power alternative to bipolar logic
- Full Military Temperature Range

## Ordering Information

The following part suffixes apply:

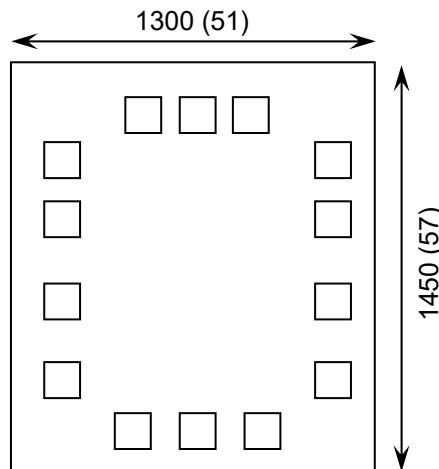
- No suffix - MIL-STD-883 /2010B Visual Inspection
- "H" - MIL-STD-883 /2010B Visual Inspection + MIL-PRF-38534 Class H LAT
- "K" - MIL-STD-883 /2010A Visual Inspection (Space) + MIL-PRF-38534 Class K LAT

LAT = Lot Acceptance Test.

For further information on LAT process flows see below.

[www.siliconsupplies.com/quality/bare-die-lot-qualification](http://www.siliconsupplies.com/quality/bare-die-lot-qualification)

## Die Dimensions in $\mu$ m (mils)



## Supply Formats:

- Default – Die in Waffle Pack (400 per tray capacity)
- \* Sawn Wafer on Tape – On request
- Unsawn Wafer – On request
- Die Thickness <> 350 $\mu$ m(14 Mils) – On request
- Assembled into Ceramic Package – On request

## Mechanical Specification

Die Size (Unsawn)	1300 x 1450 51 x 57	$\mu$ m mils
Minimum Bond Pad Size	130 x 130 5.12 x 5.12	$\mu$ m mils
Die Thickness	350 ( $\pm 20$ ) 13.78 ( $\pm 0.79$ )	$\mu$ m mils
Top Metal Composition	Al 1%Si 1.1 $\mu$ m	
Back Metal Composition	N/A – Bare Si	



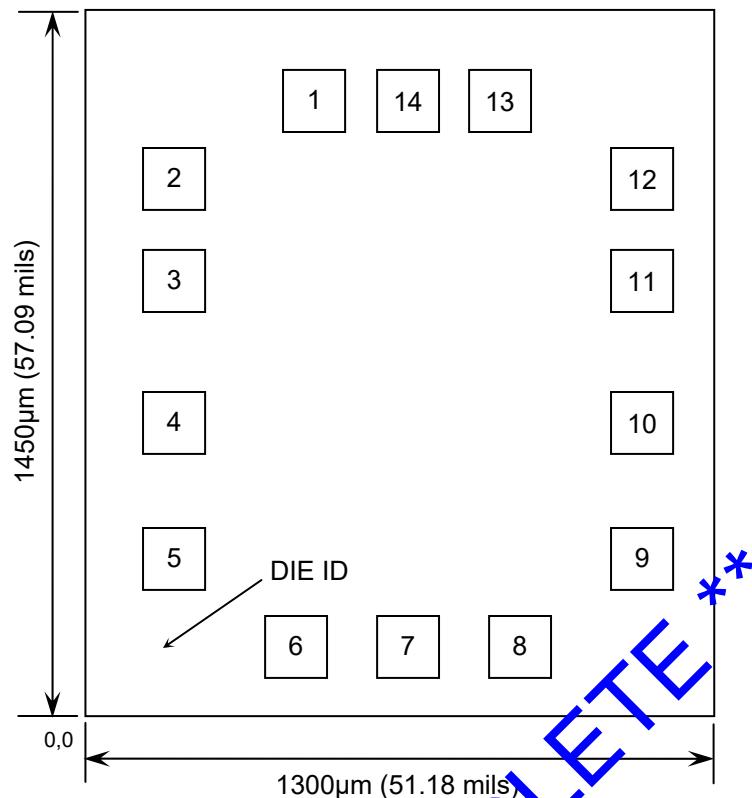


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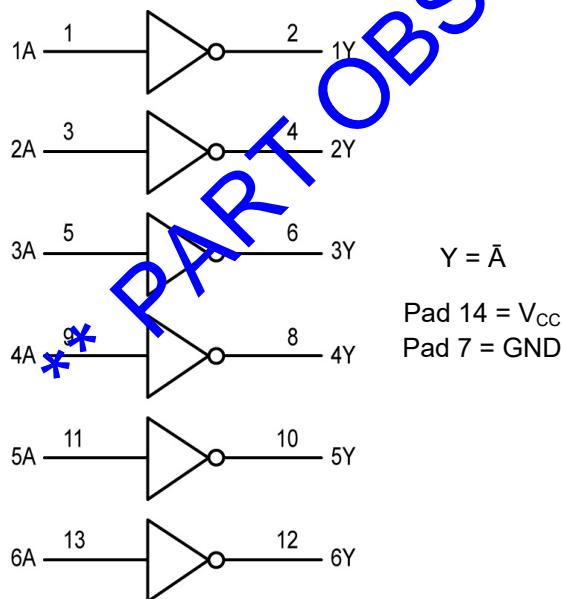
## Pad Layout and Functions



PAD	FUNCTION	COORDINATES (mm)	
		X	Y
1	1A	0.410	1.200
2	1Y	0.120	1.040
3	2A	0.120	0.830
4	2Y	0.120	0.540
5	3A	0.120	0.260
6	3Y	0.370	0.080
7	GND	0.600	0.080
8	4Y	0.830	0.080
9	4A	1.080	0.260
10	5Y	1.080	0.540
11	5A	1.080	0.830
12	6Y	1.080	1.040
13	6A	0.790	1.200
14	V <sub>CC</sub>	0.600	1.200

CONNECT CHIP BACK TO V<sub>CC</sub> OR FLOAT

## Logic Diagram



## Truth Table

INPUTS	OUTPUT
A	
H	L
L	H
H = High level (steady state)	
L = Low level (steady state)	



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## Absolute Maximum Ratings<sup>1</sup>

PARAMETER	SYMBOL	VALUE	UNIT
DC Supply Voltage (Referenced to GND)	V <sub>CC</sub>	-0.5 to +7.0	V
DC Input Voltage (Referenced to GND)	V <sub>IN</sub>	-0.5 to V <sub>CC</sub> +0.5	V
DC Output Voltage (Referenced to GND)	V <sub>OUT</sub>	-0.5 to V <sub>CC</sub> +0.5	V
DC Input Current	I <sub>IN</sub>	±20	mA
DC Output Current, per pad	I <sub>OUT</sub>	±50	mA
DC Supply Current, V <sub>CC</sub> or GND, per pad	I <sub>CC</sub>	±50	mA
Power Dissipation in Still Air <sup>2</sup>	P <sub>D</sub>	750	mW
Storage Temperature Range	T <sub>STG</sub>	-65 to 150	°C

1. Operation above the absolute maximum rating may cause device failure. Operation at the absolute maximum ratings, for extended periods, may reduce device reliability. 2. Measured in plastic DIP package, results in die form are dependent on die attach and assembly method.

## Recommended Operating Conditions<sup>3</sup> (Voltages Referenced to GND)

PARAMETER	SYMBOL	MIN	MAX	UNITS
DC Supply Voltage	V <sub>CC</sub>	4.5	5.5	V
DC Input or Output Voltage	V <sub>IN</sub> , V <sub>OUT</sub>	0*	V <sub>CC</sub>	V
Operating Temperature Range	T <sub>J</sub>	-55*	+125	°C
Output current - High	I <sub>OH</sub>	-	-24	mA
Output current - Low	I <sub>OL</sub>	-	24	mA
Input Rise or Fall rate (V <sub>IN</sub> from 0.8V to 2V)	V <sub>CC</sub> = 4.5V ΔV/ΔT	0	10	ns/V
	V <sub>CC</sub> = 5.5V	0	8	

3. This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V<sub>IN</sub> and V<sub>OUT</sub> should be constrained to the range GND ≤ (V<sub>IN</sub> or V<sub>OUT</sub>) ≤ V<sub>CC</sub>. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V<sub>CC</sub>). Unused outputs must be left open.

## DC Electrical Characteristics (Voltages referenced to GND)

PARAMETER	SYMBOL	V <sub>CC</sub>	CONDITIONS	LIMITS			UNITS
				25°C	85°C	FULL RANGE <sup>4</sup>	
Minimum High-Level Input Voltage	V <sub>IH</sub>	4.5V	V <sub>OUT</sub> = 0.1V or V <sub>CC</sub> -0.1V	2	2	2	V
		5.5V		2	2	2	
Maximum Low-Level Input Voltage	V <sub>IL</sub>	4.5V	V <sub>OUT</sub> = 0.1V or V <sub>CC</sub> -0.1V	0.8	0.8	0.8	V
		5.5V		0.8	0.8	0.8	
Minimum Low-Level Output Voltage	V <sub>OL</sub>	4.5V	I <sub>OUT</sub> = 50µA	0.1	0.1	0.1	V
		5.5V		0.1	0.1	0.1	
		4.5V	V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> <sup>5</sup> I <sub>OL</sub> = 24mA	0.36	0.44	0.50	V
		5.5V		0.36	0.44	0.50	
		4.5V	V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> <sup>5,6</sup> I <sub>OL</sub> = 50mA	-	-	1.65	V
		5.5V		-	-	1.65	

4. -55°C ≤ T<sub>J</sub> ≤ +125°C 5. All outputs loaded; thresholds on input associated with output under test. 6. Test time 1sec max, measurement made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 75Ω transmission-line drive capability at 125°C





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## DC Electrical Characteristics Continued (Voltages referenced to GND)

PARAMETER	SYMBOL	V <sub>CC</sub>	CONDITIONS	LIMITS			UNITS
				25°C	85°C	FULL RANGE	
Minimum High-Level Output Voltage	V <sub>OH</sub>	4.5V	I <sub>OUT</sub> = 50µA	4.4	4.4	4.4	V
		5.5V		5.4	5.4	5.4	
		4.5V	V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> <sup>5</sup>	3.86	3.76	3.7	V
		5.5V	I <sub>OH</sub> = -24mA	4.86	4.76	4.7	
Maximum Input Leakage Current	I <sub>IN</sub>	5.5V	V <sub>IN</sub> = V <sub>CC</sub> or GND	±0.1	±1.0	±1.0	µA
Additional Maximum I <sub>CC</sub> / Input	ΔI <sub>CCT</sub>	5.5V	V <sub>IN</sub> = V <sub>CC</sub> - 2.1V	0.6	1.5	1.6	mA
Minimum Dynamic Output Current <sup>7</sup>	I <sub>OLD</sub>	5.5V	V <sub>OLD</sub> = 1.65V Max	-	5	50	mA
	I <sub>OHD</sub>	5.5V	V <sub>OHD</sub> = 3.85V Min	-	-75	-50	
Maximum Quiescent Supply Leakage Current	I <sub>CC</sub>	5.5V	V <sub>IN</sub> = V <sub>CC</sub> or GND I <sub>OUT</sub> = 0µA	4	40	80	µA

7. Maximum test duration 2ms, one output loaded at a time.

## AC Electrical Characteristics<sup>8</sup> V<sub>CC</sub> = 5.0V ± 0.5V

PARAMETER	SYMBOL	V <sub>CC</sub>	CONDITIONS	LIMITS			UNITS
				25°C	85°C	FULL RANGE <sup>4</sup>	
Maximum Propagation Delay Input A to Output Y (Figure 1)	t <sub>PLH</sub>	5.0V	C <sub>L</sub> = 50pF, Input tr = tf = 3.0ns	8.5	9	9.3	ns
	t <sub>PHL</sub>	5.0V		8	8.5	9.3	
Maximum Input Capacitance	C <sub>IN</sub>	5.0V	T <sub>J</sub> = 25°C	TYPICAL			pF
Power Dissipation Capacitance	C <sub>PD</sub>	5.0V	T <sub>J</sub> = 25°C, C <sub>L</sub> = 50pF	4.5			pF

8. Not production tested in die form, characterized by chip design and tested in package.





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## Switching Waveform

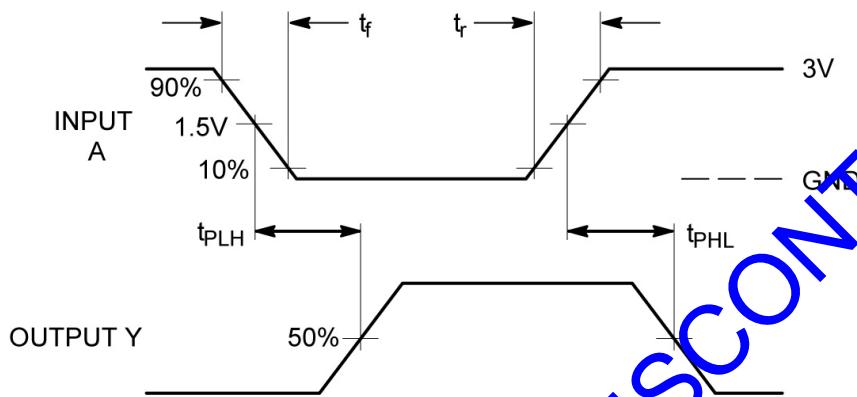
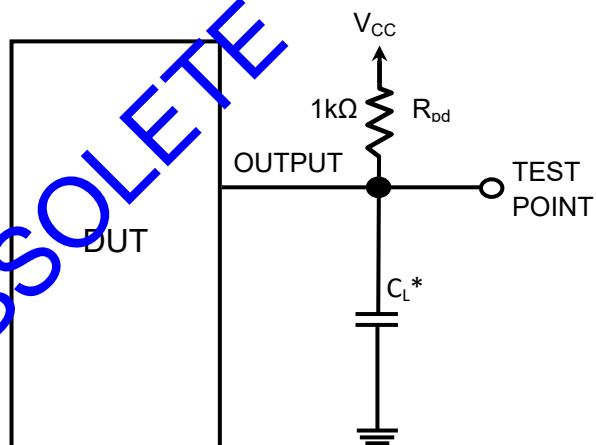


Figure 1 – Propagation delay, Input A to Output Y

## Test Circuit



\* Includes all probe and jig capacitance

Figure 2 - Test Circuit

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